

## Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier                  |   | User Part Number  |           |            |           |  |
|---------------------------|---|---|-----------|------------|-----------|--|
| Nexperia B.V.             |   | BAV23A-Q  |           |            |           |  |
| Name of Laboratory        |   | Part Description  |           |            |           |  |
| Assembly reliability labs |   | Nexperia DHAM Small Signal Bipolar Diode<br>SMD package |           |            |           |  |
| Based on AEC-Q101 Test    | Test Conditions   | Duration  | # Lots    | # Quantity | # Rejects |  |
| # E1                      | <b>TEST</b><br>Pre- and Post-Stress<br>Electrical Test<br>Tamb = 25 °C  | N/A   | see below | all parts  | see below |  |
| # A1                      | <b>PC</b><br>Preconditioning<br>JESD22-A113<br>Bake Tamb = 125 °C<br>Soak Tamb = 85 °C, RH = 85%<br>Reflow soldering  | 24 hours<br>168 hours<br>3 cycles                       | 1514      | 64430      | 0         |  |
| # B1                      | <b>HTRB</b><br>High Temperature Reverse<br>Bias<br>MIL-STD-750-1<br>M1038 Method A<br>Tj = Tjmax, Vr = 100% of max. datasheet<br>reverse voltage              | 1000 hours  | 110       | 4920       | 0         |  |
| # A4                      | <b>TC</b><br>Temperature Cycling<br>JESD22-A104<br>-65 °C to Tjmax, not to exceed 150°C   | 1000 cycles   | 311       | 14080      | 0         |  |
| # A3 or                   | <b>UHAST</b><br>Unbiased HAST<br>JESD22-A118<br>Tamb = 130 °C, RH = 85 %  | 96 hours  | 311       | 14080      | 0         |  |
| # A3 alt                  | <b>AC</b><br>Autoclave<br>JESD22-A102<br>Tamb = 121 °C, RH = 100 %<br>Pressure = 205 kPa (29.7 psia)  |   |           |            |           |  |
| # A2 alt                  | <b>H3TRB</b><br>High Humidity High<br>Temperature Reverse Bias<br>JESD22-A101<br>Tamb = 85 °C, RH = 85%, VR = 80 % of<br>rated reverse voltage <sup>[1]</sup> | 1000 hours  | 311       | 14080      | 0         |  |
| # A5                      | <b>IOL</b><br>Intermittent Operating Life<br>MIL-STD-750 Method 1037<br>ton = toff, devices powered to insure ΔTj =<br>100 °C for 15000 cycles                | 1000 hours  | 312       | 14120      | 0         |  |
| # C8                      | <b>RSH</b><br>Resistance to Solder Heat<br>JESD22-A111<br>260 °C ± 5 °C   | 10 s  | 269       | 8070       | 0         |  |
| # C10                     | <b>SD</b><br>Solderability<br>J-STD-002   |   | 222       | 6660       | 0         |  |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

### Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab        | Technology                 | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|------------------|----------------------------|----------|---------|--------------------|------------|
| Nexperia<br>DHAM | Small Signal Bipolar Diode | 4920     | 0       | 0,86               | 1,16E+09   |

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